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			1		2 3					4 5	<u> </u>
	PRODUCT NUMBER	NO. OF CONTACTS	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F	BOARD THICKNESS	PLATING	
() [89648-001	160	0.000/55.00	.092/2.34	.975/24.76	2.050/52.07	2.150/54.61	.082/2.08	.062/1.58	NOTE 3	
	89648-002	160	2.200/55.88	.155/3.94	.973/24.76	2.030/32.07	2.130/34.61	.144/3.66	.125/3.18	NOTE 4	
	89648-001LF	160	2.200/55.88	.092/2.34	.975/24.76	2.050/52.07	2.150/54.61	.082/2.08	.062/1.58	NOTE 3	
	89648-002LF		2.200/ 33.00	.155/3.94	1070/21170	21000, 02107	21100,01101	.144/3.66	.125/3.18	NOTE 4	
<u>A</u>	0	OARD HOLES RIALS : DIELEC CONTA	ACTS : Cu Be								_A
	FRAME: ZINC ALLOY #3 3 PLATING: -001 SOLDER TAILS: 150u"/3.81um Sn Pb FRAME: 100u"/2.54um NICKEL CONTACT: 30u"/.76um GXT OVER 50u"/1.27um Ni LEAD FREE OPTION: SOLDER TAILS: 150u"/3.81um Sn FRAME: 100u"/2.54um NICKEL CONTACT: 30u"/.76um GXT OVER 50u"/1.27um Ni										
В шоэ	(4) PLATING: -002 SOLDER TAILS: 150u"/3.81um Sn Pb FRAME: 150u"/3.81um SnPb CONTACT: 30u"/.76um GXT OVER 50u"/1.27um Ni LEAD FREE OPTION: SOLDER TAILS: 150u"/3.81um Sn FRAME: 150u"/3.81um Sn										В
FCIconnect	CONTACT: 30u"/.76um GXT OVER 50u"/1.27um Ni (5) DO NOT REMOVE PROCESSING CAP UNTIL SOLDERING IS COMPLETED. CAP WILL PREVENT POTENTIAL NOSE PIECE BOW DURING HIGH TEMP. SOLDERING PROCESS. (6) .002/0.05 MAX BURR PERMITTED. (7) PART NUMBERS WITH LF AT THE END ARE LEAD FREE.										
	8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 20 SECONDS IN A CONVECTION, INFRA—RED OR VAPOR PHASE REFLOW										
C	MINIMUM THICK CIRCUIT BOARD. SEE APLICATION NOTES/PROCEDURES IF THEY ARE AVAILABLE (a) IF "LF" P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008. (b) 150 1302 150 1401 150										С
Copyright FCI											
	0°±2° xxxx±.0020/.051 scale 2:1 RECEPT. DBL MC										3
D [orm: A3		1		2		3	index s	heet	4 5	D 6